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**INLINE DIE-ATTACH**  
**ME8650-RC**

- Flexible**
- Moisture Resistant**
- High Green Strength**
- 100% Solid**
- Epoxy Paste Adhesive**

**IDEAL FOR:**

- "Low" Bleeding
- Large Area Die Attach
- High Temperature Wirebondable
- Component Attach
- Substate Attach

**DESCRIPTION:**

ME8650-RC is designed for needle dispensing and screen-printing processing. This silver filled conductive die-attach adhesive can be rapidly cured at low temperatures. This single component, silver filled paste is ambient storable electrically and thermally conductive. It is highly thixotropic with minimal sag.

ME8650-RC has been designed to minimize bleeding on both silver plated copper and alloy 42 leadframes. Maintains more than 100 psi bond strength at 250°C for wire-bonding.

**AVAILABILITY:**

ME8650-RC is available in syringes or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 min. before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to the recommended schedules.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 60 minute )	<5x10 <sup>-4</sup> ohm-cm
Dielectric Strength (Volts/mil)	>Not Applicable
Glass Transition Temp.(°C)	-20/-50 Minor ±10%
Current Carrying Capabilities	50 Amp/mm <sup>2</sup>
Lap-Shear Strength	N/A
Device Push-off Strength	>1500 psi >10.3 N/mm <sup>2</sup>
Hardness (Type)	80 (A) ±10%
Cured Density (gm/cc)	3.5 ±10%
Thermal Conductivity	>55 Btu-in/hr-ft <sup>2</sup> -°F ±10% >7.9 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	100 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(5.0 rpm, 25°C) (Brookfield DV-1,spindle CP51)	18,000 cp ±20%

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

Temperature	Time	Pressure
80°C	120 min	
100°C	60 min	
125°C	30 min	
150°C	15 min	
175°C	8 min	

Pot life: 25°C for >5 days.

**SHELF LIFE:**

Storage temperature	Shelf Life
-40°C	1 yr
25°C	30 day

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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